



Material Content Data Sheet



Sales Product Name		BGT 24MTR11 E6327		Issued		25. September 2017		
MA#		MA001093988						
Package		PG-VQFN-32-9		Weight*		55.62 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.627	2.92	2.92	29242	29242
leadframe	inorganic material	phosphorus	7723-14-0	0.008	0.01		145	
	non noble metal	zinc	7440-66-6	0.032	0.06		582	
	non noble metal	iron	7439-89-6	0.647	1.16		11638	
wire	non noble metal	copper	7440-50-8	26.284	47.27	48.50	472543	484908
	noble metal	gold	7440-57-5	0.571	1.03	1.03	10265	10265
	encapsulation	organic material	carbon black	1333-86-4	0.072	0.13		1290
encapsulation	plastics	epoxy resin	-	3.039	5.46		54630	
	inorganic material	silicondioxide	60676-86-0	20.816	37.42	43.01	374238	430158
leadfinish	non noble metal	tin	7440-31-5	1.435	2.58	2.58	25802	25802
plating	noble metal	silver	7440-22-4	0.555	1.00	1.00	9978	9978
glue	plastics	epoxy resin	-	0.123	0.22		2219	
	noble metal	silver	7440-22-4	0.413	0.74	0.96	7428	9647
*deviation	< 10%					Sum in total:	100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com